I claim:

1. A method for wireless communication among first and second integrated circuit devices within an enclosure, said method comprising the steps of:

transmitting a signal using a first antenna associated with said first integrated circuit device; and

receiving said signal using a second antenna associated with said second integrated circuit device within said enclosure.

2. The method of claim 1, wherein said first and second antennas are incorporated in said first and second integrated circuit devices.

3. The method of claim 2, wherein at least one of said first and second antennas is a pin on said first or second integrated circuit device.

4. The method of claim 2, wherein at least one of said first and second antennas is printed on said first or second integrated circuit device.

5. The method of claim 1, wherein said signal comprises one or more channels.

6. The method of claim 1, wherein one or more signals are transmitted by said first antenna using one or more associated sub-carrier frequencies.

7. The method of claim 1, wherein said signal is time-division multiplexed.

8. The method of claim 1, wherein said signal is frequency-division multiplexed.

9. The method of claim 1, wherein said signal is spatially multiplexed.

10. The method of claim 1, wherein said enclosure is a housing of a self-contained device.

11. The method of claim 1, wherein said signal is transmitted in accordance with an 802.11 wireless standard.

12. The method of claim 1, wherein said signal is transmitted in accordance with an ultra wide band wireless standard.

13. The method of claim 1, wherein said signal is transmitted in accordance with a Bluetooth standard.

14. A method for wireless communication by an integrated circuit device within an enclosure, said method comprising the step of:

transmitting a signal using an antenna associated with said integrated circuit device to a second integrated circuit device within said enclosure.

15. The method of claim 14, wherein said signal comprises one or more channels.

16. The method of claim 14, wherein said enclosure is a housing of a self-contained device.

17. An integrated circuit device within an enclosure, comprising:

at least one circuit; and

an antenna for transmitting a signal to a second integrated circuit device within said enclosure.

18. The integrated circuit device of claim 17, wherein said signal comprises one or more channels.

19. The integrated circuit device of claim 17, wherein said enclosure is a housing of a self-contained device.

20. The integrated circuit device of claim 17, wherein said antenna is incorporated in said integrated circuit device.

21. The integrated circuit device of claim 17, wherein said antenna is at least one pin of said integrated circuit device.